

JUNCTION FIELD EFFECT TRANSISTOR 2SK3230

N-CHANNEL SILICON JUNCTION FIELD EFFECT TRANSISTOR FOR IMPEDANCE CONVERTER OF ECM

DESCRIPTION

The 2SK3230 is suitable for converter of ECM.

FEATURES

- Compact package
- High forward transfer admittance
1000 μS TYP. ($I_{\text{DSS}} = 100 \mu\text{A}$)
1600 μS TYP. ($I_{\text{DSS}} = 200 \mu\text{A}$)
- Includes diode and high resistance at G - S

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3230	SC-89 (TUSM)

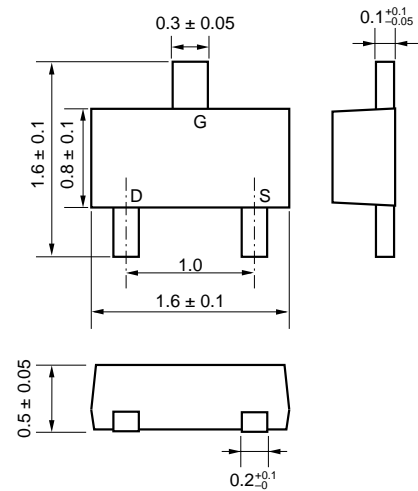
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Drain to Source Voltage ^{Note1}	V_{DSX}	20	V
Gate to Drain Voltage	V_{GDO}	-20	V
Drain Current	I_{D}	10	mA
Gate Current	I_{G}	10	mA
Total Power Dissipation ^{Note2}	P_{T}	200	mW
Junction Temperature	T_{J}	125	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

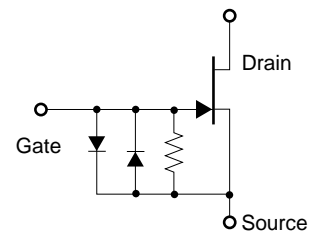
- Notes 1.** $V_{\text{GS}} = -1.0 \text{ V}$
2. Mounted on ceramic substrate of $3.0 \text{ cm}^2 \times 0.64 \text{ mm}$

Remark Please take care of ESD (Electro Static Discharge) when you handle the device in this document.

PACKAGE DRAWING (Unit: mm)



EQUIVALENT CIRCUIT



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 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

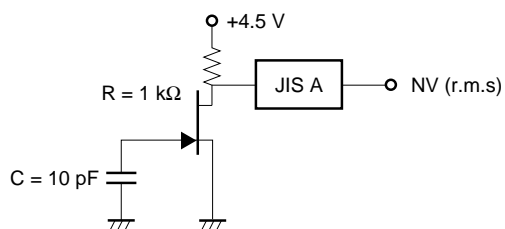
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Cut-off Current	I _{DSS}	V _{DS} = 5.0 V, V _{GS} = 0 V	40		600	μA
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = 5.0 V, I _D = 1.0 μA	-0.1		-1.0	V
Forward Transfer Admittance	y _{fs1}	V _{DS} = 5.0 V, I _D = 30 μA, f = 1.0 kHz	350			μS
Forward Transfer Admittance	y _{fs2}	V _{DS} = 5.0 V, V _{GS} = 0 V, f = 1.0 kHz	350			μS
Input Capacitance	C _{iss}	V _{DS} = 5.0 V, V _{GS} = 0 V, f = 1.0 MHz		7.0	8.0	pF
Noise Voltage	NV	See Test Circuit		1.8	3.0	μV

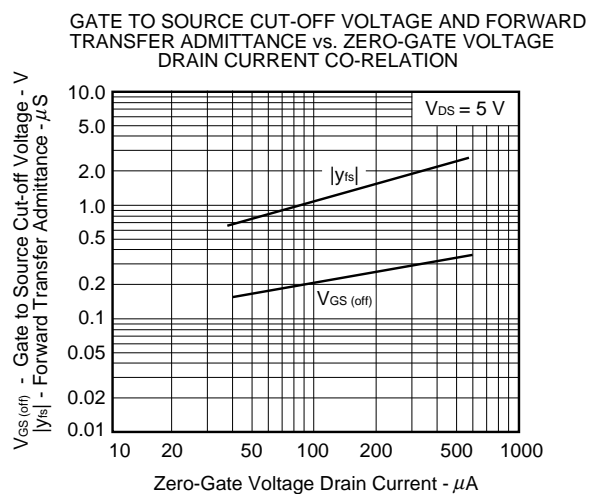
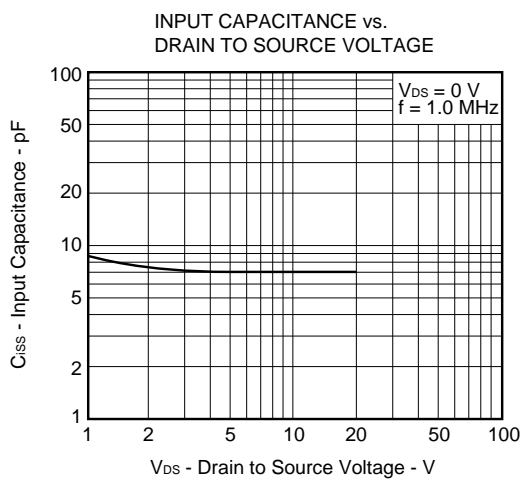
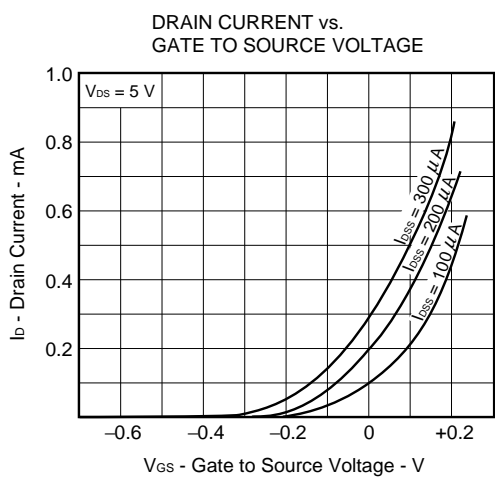
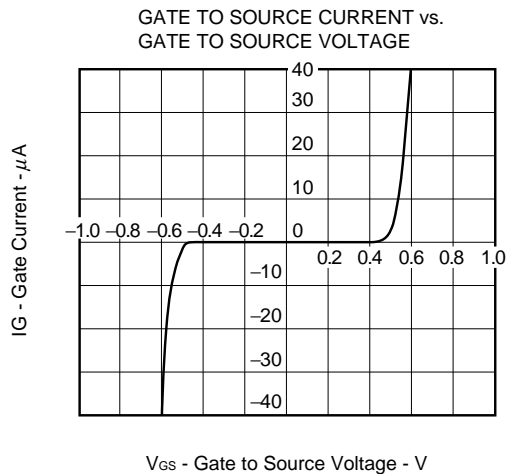
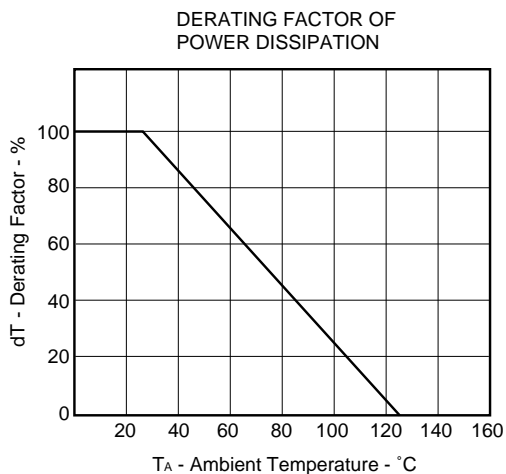
I_{DSS} RANK

MARKING	J2	J3	J4	J5	J6	J7
I _{DSS} (μA)	40 to 70	60 to 110	90 to 180	150 to 300	200 to 450	300 to 600

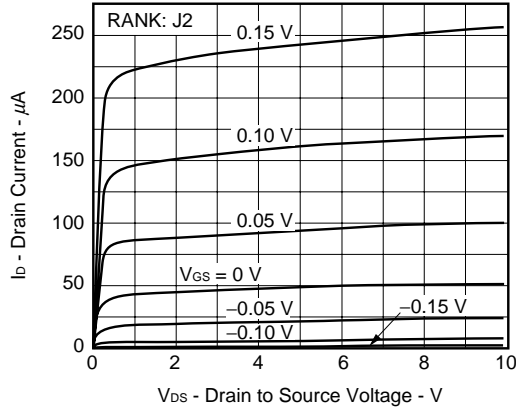
NOISE VOLTAGE TEST CIRCUIT



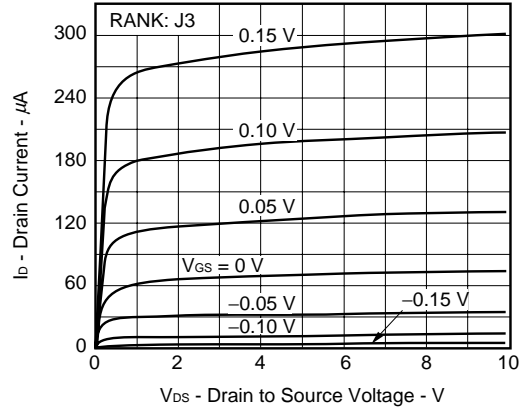
TYPICAL CHARACTERISTICS (T_A = 25°C)



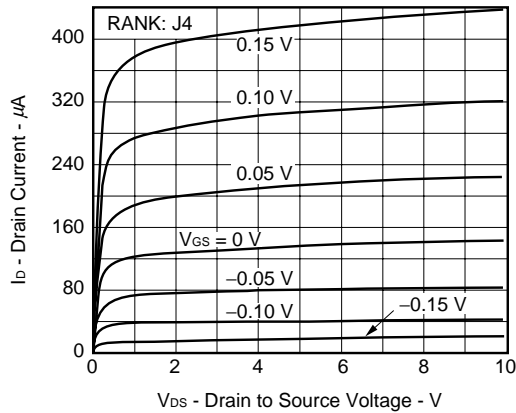
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



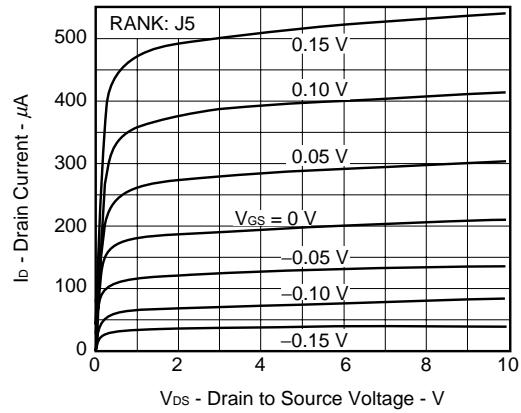
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



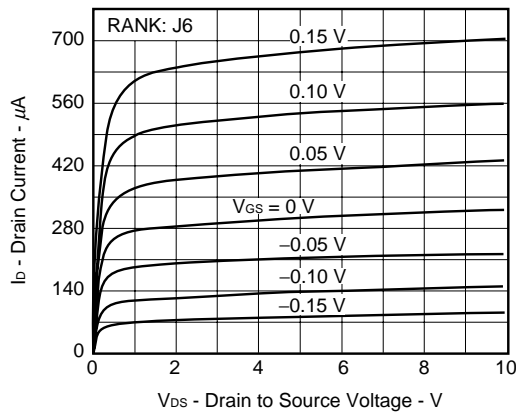
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



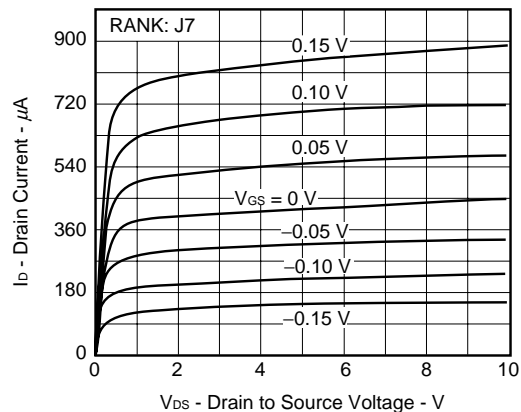
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



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